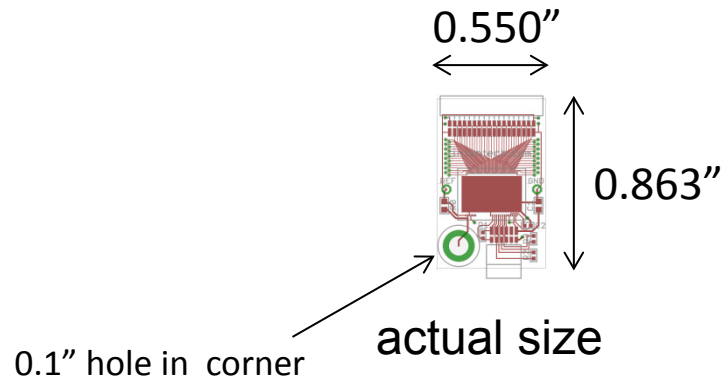


# RHD2164 Headstage 1 Board

FR406 material, 0.036" thick, ENIG (immersion gold) plating (2  $\mu$ m)

No through-hole components; only SMDs



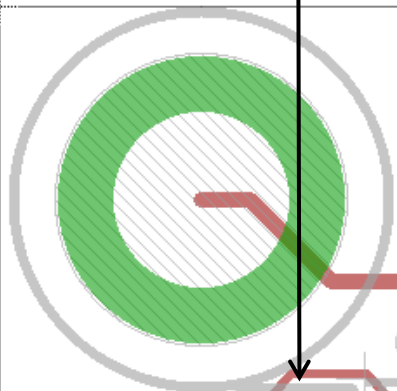
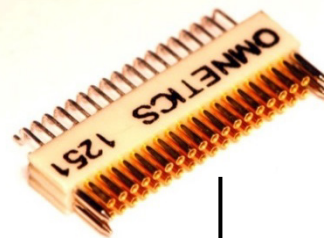
# Top Components (9 total)

Omnetics A79623  
connector

R1: 100  $\Omega$  (0201)

R0: 0  $\Omega$  (0402)

Omnetics A79025  
connector



1 pad not bonded  
RHD2164 bare die  
(7.3 mm x 4.2 mm,  
0.20 mm thick)

85 total bondwires

3 pads not bonded



R2: 100  $\Omega$  (0201)

R3: 100  $\Omega$  (0201)

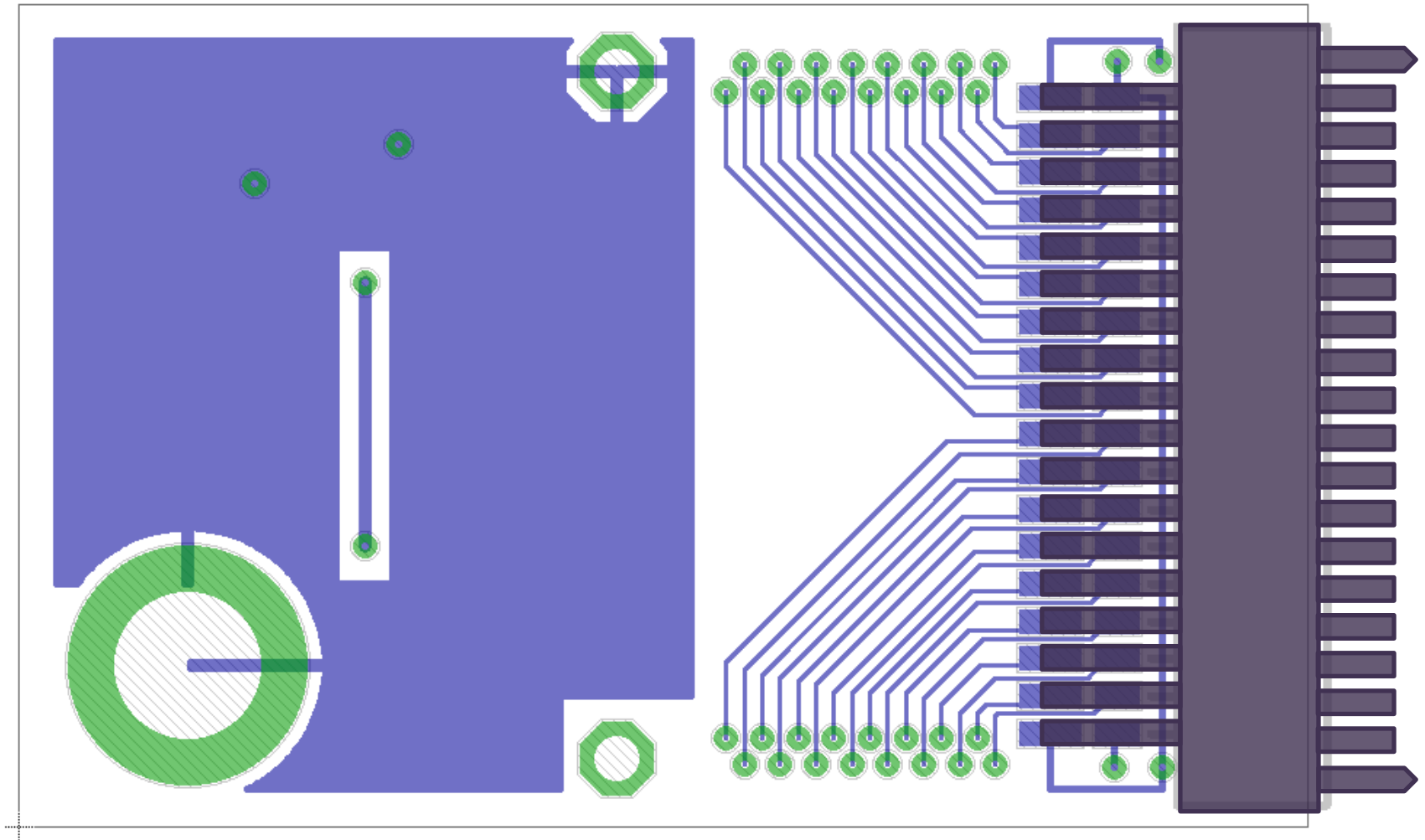
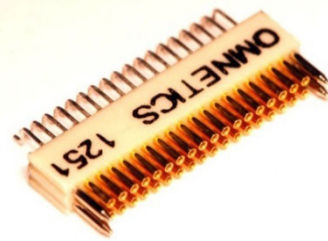
C2: 0.01  $\mu\text{F}$  (0201)

C1: 0.1  $\mu\text{F}$  (0402)

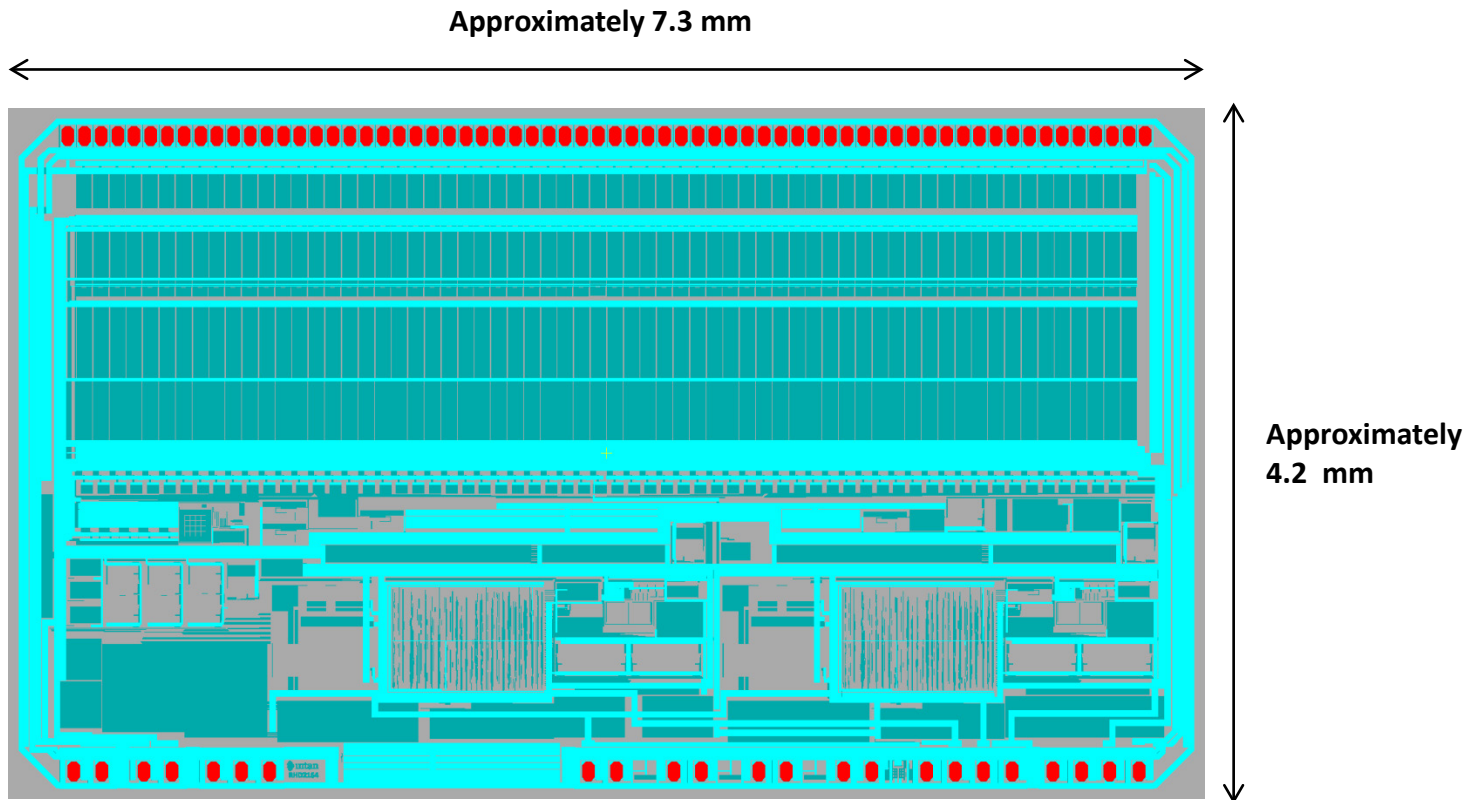


## Bottom Components (1 total)

Omnetics A79025  
connector



# Intan Technologies RHD2164 Bare Die



**Gray** = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

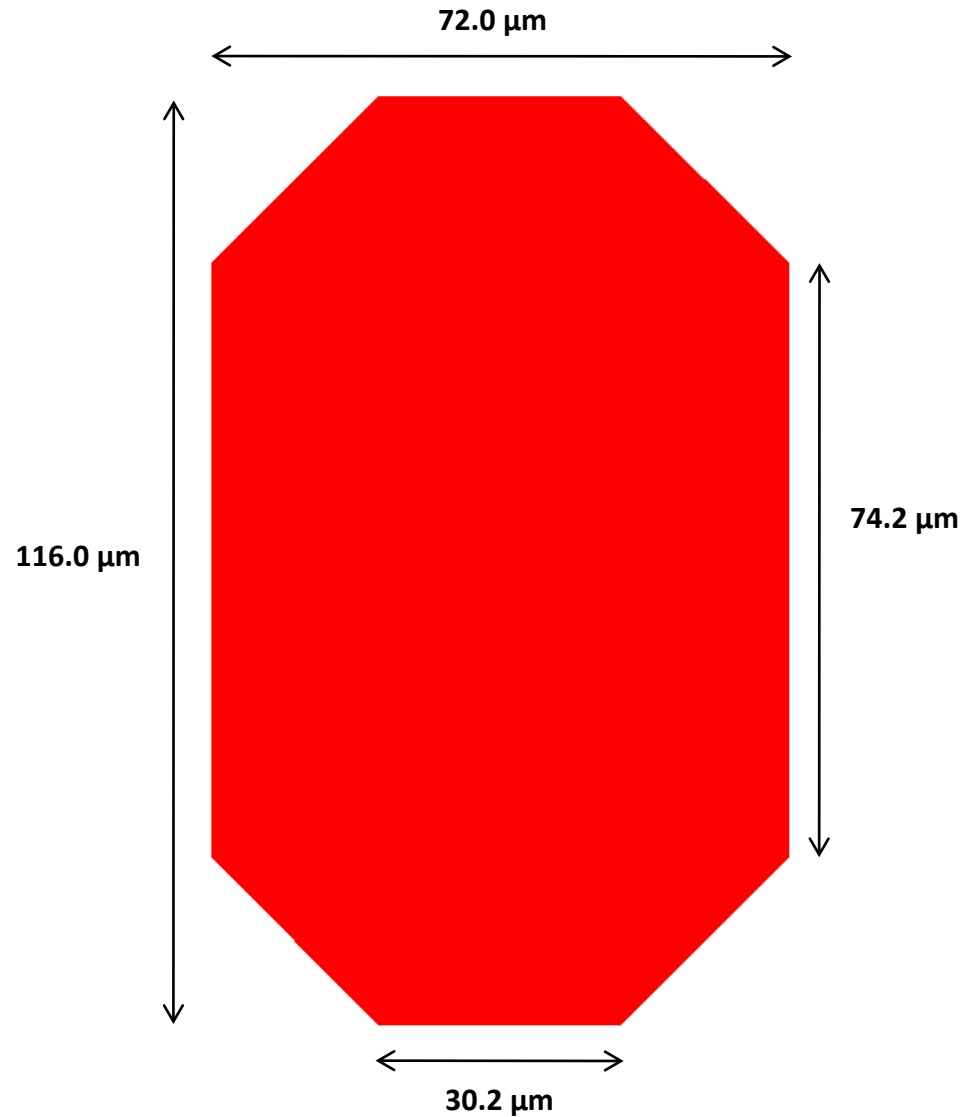
**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads

Each die is 0.20 mm (8 mils) thick

## Bond Pad Dimensions

Bond pad metal: AlCu (99.5% aluminum, 0.5% copper)



Minimum bond pad pitch (center to center) on RHD2164:  $101.6\ \mu\text{m}$  (4.000 mil)